

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3329	(current voltage power electric\$3 field) with (preform preform adhesiv\$3) with (melt\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/22 17:53
L2	274	(current voltage power electric\$3 field) with (preform preform adhesiv\$3) with (melt\$3) same (cover lid cap)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/22 17:53
L3	50	(current voltage power electric\$3 field) with (preform preform adhesiv\$3) with (melt\$3) same (cover lid cap) same (base substrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/22 18:04
L4	15	(current voltage power electric\$3 field) with (solder) with (preform preform adhesiv\$3) with (melt\$3) same (cover lid cap) same (base substrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/22 18:05
L5	19	((current voltage power) (electric\$ near field)) with (solder) with (preform preform adhesiv\$3) with (melt\$3) same (base substrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/22 18:05
L6	13	((current voltage power) (electric\$ near field)) with (solder) with (preform preform adhesiv\$3) with (melt\$3) with (base substrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/22 18:05
L7	13	((current voltage power) (electric\$ near field)) with (solder) with (preform pre-form adhesiv\$3) with (melt\$3) with (base substrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/22 18:12
L8	14	((current voltage power) (electric\$ near field)) with (solder) with (preform pre-form adhesiv\$3 braz\$3) with (melt\$3) with (base substrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/22 18:12
L9	171	((current voltage power) (electric\$ near field)) with (solder) with (preform pre-form adhesiv\$3 braz\$3) with (base substrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/22 18:13

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L10	14	((current voltage power) (electric\$ near field)) with (solder) with (preform pre-form adhesiv\$3 braz\$3) with (base substrate wafer) with (cap lid cover)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/22 18:13
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